Form PTO-1595 (Rev. 10/02)IOMB No. 0651-0027 (exp. 6/30/2005) Tab settings \Rightarrow \Rightarrow \Rightarrow \checkmark 10278;	
	Please record the attached original documents or copy thereof.
1. Name of conveying party(ies): LEE, Su Gueon	2. Name and address of receiving party(ies) Name: <u>HYNIX SEMICONDUCTOR INC</u>
Additional name(s) of conveying party(ies) attached?	
3. Nature of conveyance: Assignment Merger	
	Street Address:San 136-1, Ami-ri,
Security Agreement Change of Name	Bubal-eub, Ich'on, Kyoungki-do,
Q Other	Republic of Korea
T 0 000/	City:State:Zip:
Execution Date: June 9, 2004	Additional name(s) & address(es) attached? 🖵 Yes 🎽 No
4. Application number(s) or patent number(s):	June 9, 2004
	lication, the execution date of the application is:
A. Patent Application No.(s) 10/875477 Additional numbers a	B. Patent No.(s)
5. Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Name: Richard J. Streit	7. Total fee (37 CFR 3.41)\$_40.00
Internal Address:	Authorized to be charged to deposit account
Street Address:C/o_Ladas & Parry	8. Deposit account number:
	12-0400
224 South Michigan Avenue City: Chicago State: IL Zip: 60604	(Attach duplicate copy of this page if paying by deposit account)
9. Statement and signature.	E THIS SPACE
To the best of my knowledge and belief, the foregoing is a true copy of the original document. Richard J. Streit Name of Person Signing Reg. 25765	Signature June 24, 2004 Date
Total number of pages including cov	er sheet, attachments, and documents:

e.

PATENT REEL: 015523 FRAME: 0126

UNITED STATES OF AMERICA

ASSIGNMENT

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

ASSIGNOR:

Name : Su Gueon LEE Address : 205-802, Hyundai 2nd Apt., 3029, Hyangjeong-dong, Cheongju, Chungcheongbukdo, Korea

(INVENTOR NAME AND ADDRESS)

hereby sells, assigns and transfers to

ASSIGNEE: Name : Hynix Semiconductor Inc. Address : San 136-1, Ami-ri, Bubal-eub, Ich'on, Kyoungki-do, Korea

(ASSIGNEE NAME AND ADDRESS)

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the invention entitled:

APPARATUS FOR SEPARATING CULL OF SEMICONDUCTOR PACKAGE MOLDING SYSTEM

(TITLE)

and which is found in (check one applicable item below)

 \square U.S. patent application executed on even date herewith

U.S. Application Serial No. ______ filed on ______

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby convenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further convenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify

PATENT REEL: 015523 FRAME: 0127

as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/we have set our hand and seal

June 9, 2004

Date

<u>4u guen, lee</u>. INVENTOR: Su Gueon LEE

Date

INVENTOR:

0699P/1

RECORDED: 06/24/2004